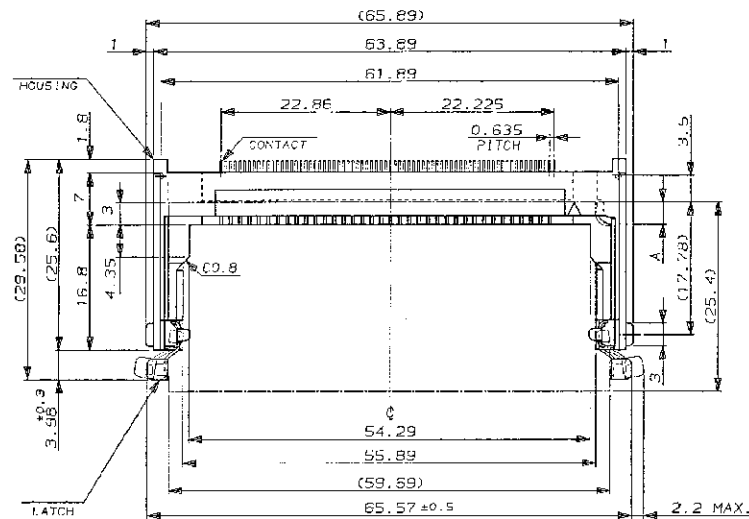
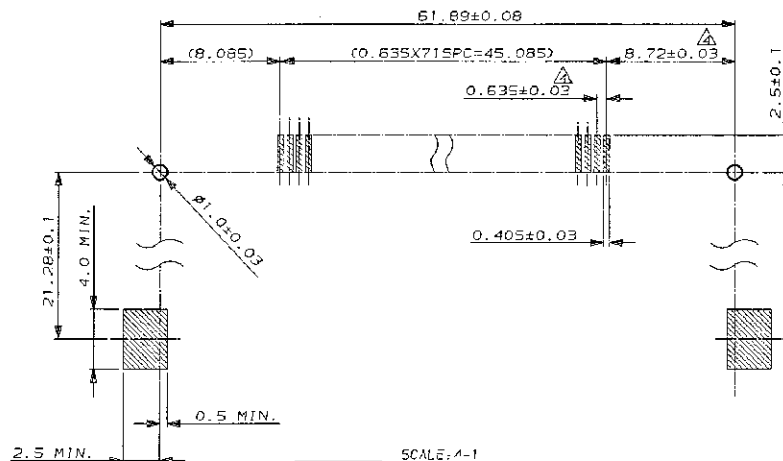
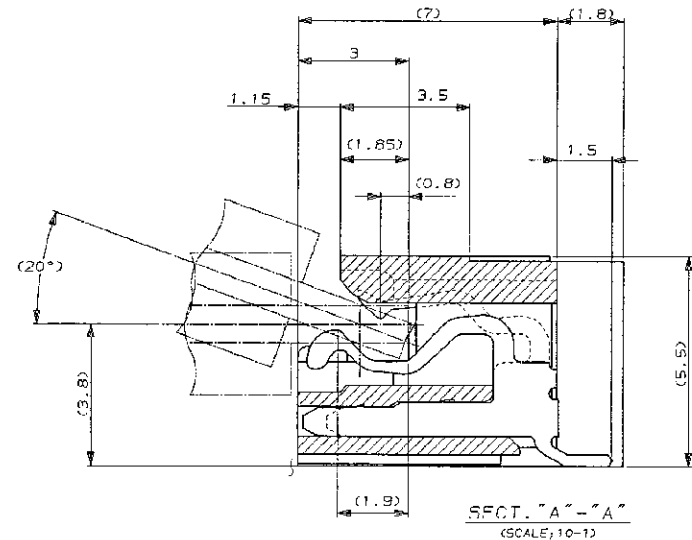


DETAIL "B"
(SCALE: 5-1)



SCALE: 4-1
P.C. BOARD LAYOUT (CONNECTOR MOUNT SIDE)



SECT. "A"- "A"
(SCALE: 10-1)

NOTES

1. MATERIAL & FINISH

HOUSING : GLASS FILLED LCP

CONTACT : COPPER ALLOY

FINISH---SEE NOTES

LATCH : COPPER ALLOY, TIN PL.

CONTACT PLATING (AU PL. TYPE)

AU (0.3µm) PL. AT CONTACT, TIN PL. AT

TINE OVER NI PL.

CONTACT PLATING (TIN PL. TYPE)

TIN PL. (2µm) OVER NI PL.

TOLERANCE : NON CUMULATIVE.

CONTACT PLATING (AU PL. TYPE)

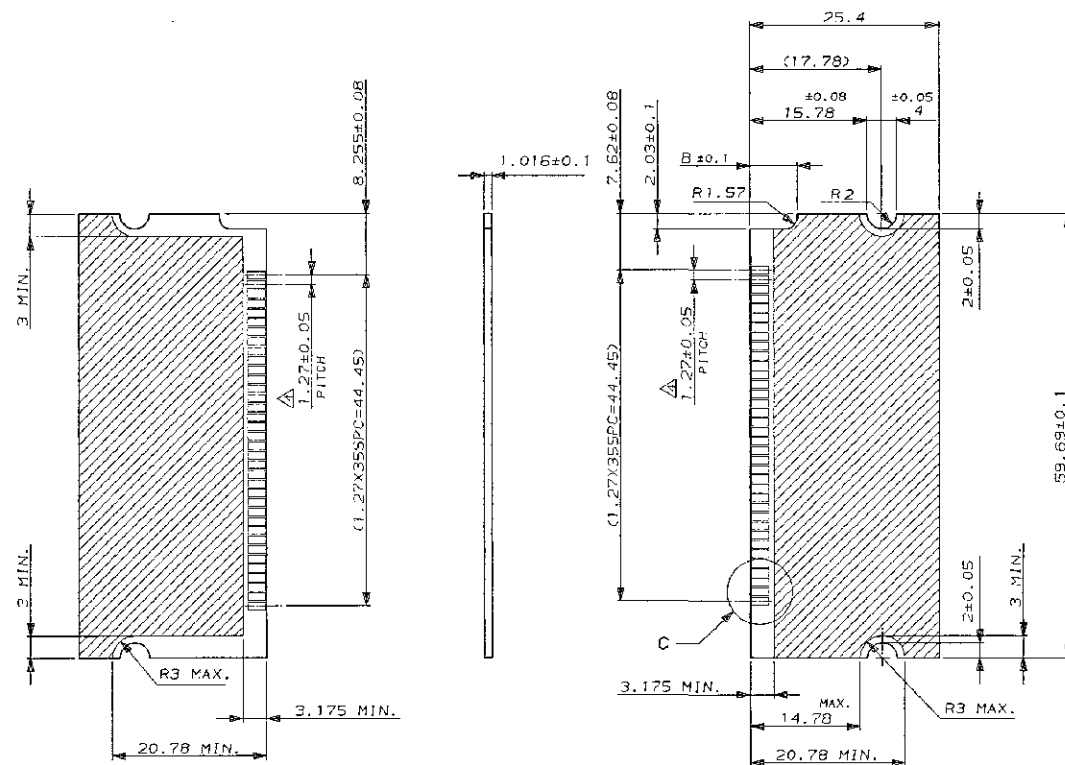
AU (1.27µm) PL. AT CONTACT, TIN PL. AT

TINE OVER NI PL.

6 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER
D.RENAUD/D.SINISI

6 OBSOLETE	NATURAL	2.95	1.27µm Au	5177827-4
6 OBSOLETE	BLACK	6.15	0.3µm Au	5177827-3
6 OBSOLETE	NATURAL	1.0	0.3µm Au	5177827-2
6 OBSOLETE	NATURAL	2.98	0.3µm Au	5177827-1
HOUSING COLOR		C	A	PLATING (CONTACT POINTS)
				PART No.

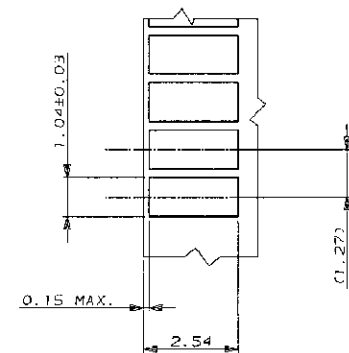
TE Connectivity		TE Connectivity	
NAME: MTH SOCKET		C J C-5177827	
MATERIAL: SEE NOTES		FINISH: SEE NOTES	
DESIGN: LEO ZHOU 15SEP05		APP: STEVEN YAO 15SEP05	
CHK: T.KAWAMAE 15SEP05		APP: STEVEN YAO 15SEP05	
P ECO-11-005033		RK HMR APR 11	
LTK (PREVISION RECORD)		DR CHC DATE	
SCALE: 2-1		SCALE: 2-1	
REV. P		SHEET 1 OF 2	



COMPONENT AREA

(SMALL OUTLINE SIMM)

RECOMMENDED DIMENSIONS OF "SMALL OUTLINE SIMM" P.C. BOARD



DETAIL C
(SCALE: 10-1)

6.35	5.0V
3.175	3.3V
8	CIRCUIT VOLTAGE



TE Connectivity

M III SOCKET

(E)	C	LOC	(NO.)	C-5177827
PS	J	(SCALE)	REV.	SHEET
3		2-1	P	3 OF 3

(CUSTOMER DRAWING)